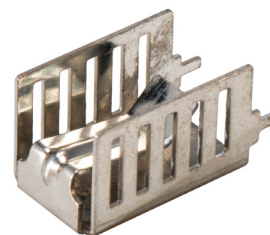




**MODEL:** HSS07-C20-P274 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- TO-220 package
- solder pin
- copper alloy
- tin plated



**MODEL**

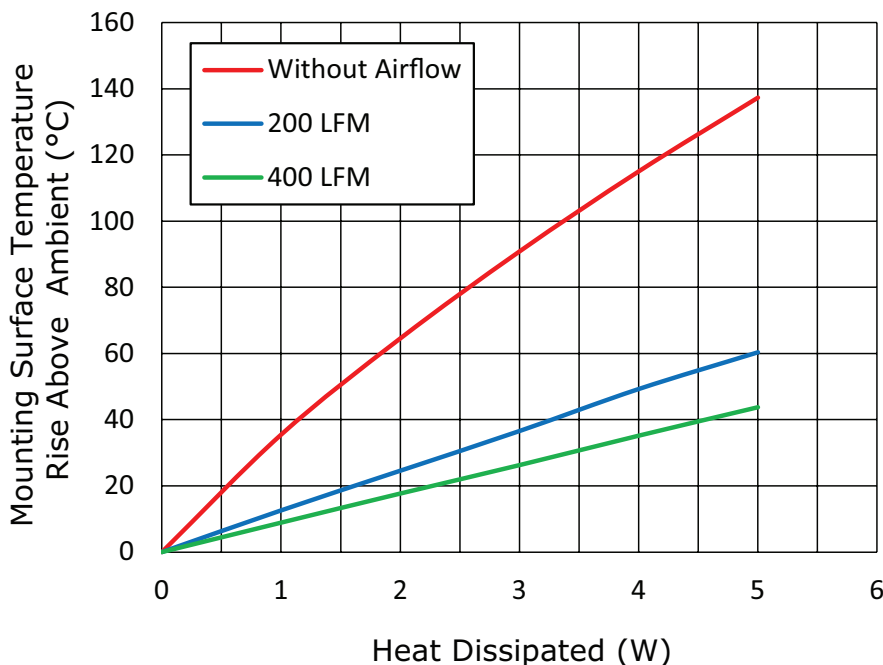
HSS07-C20-P274	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	29.57	35.5	12.6	8.9

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	35.5	12.6	8.9
2	64.5	24.6	17.7
3	90.9	36.6	26.3
4	115.1	49.3	35.2
5	137.4	60.4	43.8

Ths: "hot spot" temperature measured on the heatsink  
Ta: ambient temperature



## MECHANICAL DRAWING

units: mm  
tolerance:  $\pm 0.25$  mm

MATERIAL	C1100
FINISH	tin
THICKNESS	0.6 mm
WEIGHT	4.5 g

